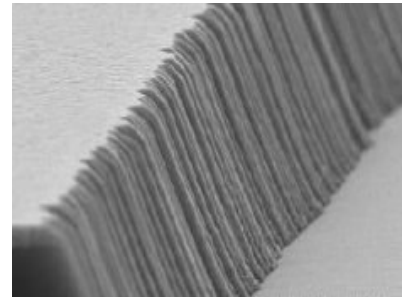


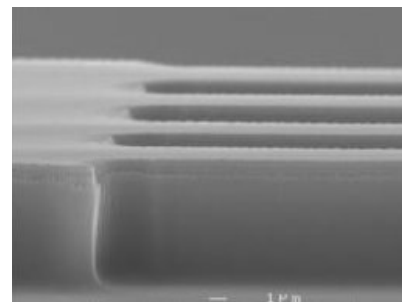
# ATS-Etcher Series High Density Plasma Etching System for Waveguides



SEM images



(a) silica



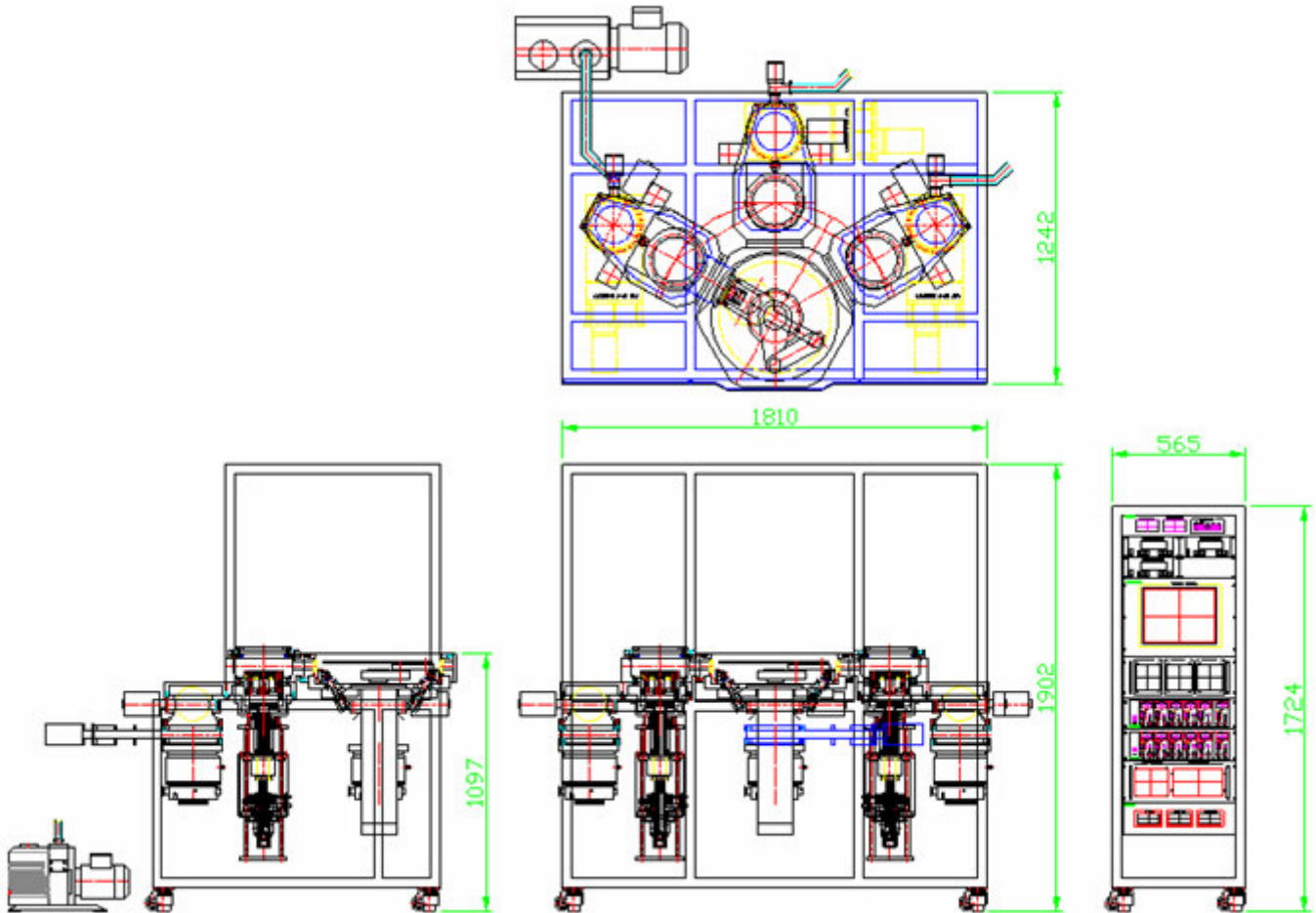
(b) polymer

## Special Features

- ◆ TCP etching system with 3 chambers for R&D and small scale production
- ◆ Automatic robot transporting system
- ◆ ESC (Electro Static Chuck) and He cooling system for silica etching
- ◆ Applications
  - Metal etching
  - Silica etching
  - Polymer etching

- ◆ Wafer capacity  
1 × 6"
- ◆ Average throughput  
Up to 250,000 wafers per year
- ◆ Dimension  
1810L × 1800H × 1222W (mm)
- ◆ Others
  - Power : AC 3kW for TCP source  
(13.56MHz)
  - AC 600W for bias voltage  
(13.56MHz)
  - Gas : CF<sub>4</sub> / O<sub>2</sub> / He / SF<sub>6</sub>
  - Substrate material : Si/SiO<sub>2</sub>
  - Pump : rotary(600l/min, 900l/min) & turbo(500l/s, 1000l/s)

◇ Layout



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